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5/18/95
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[Signature]

IN THE UNITED STATES PATENT OFFICE

Inventors: F. Kish, et al. Serial No.: 08/298,691
Filed: 31 August 1994 Examiner: W. Mintel
Group Art Unit: 2503
For: Wafer Bonding of Light Emitting Diode Layers

AMENDMENT

Honorable Assistant Commissioner of
Patents
Washington, D.C. 20231

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MAY 08 1995

MAIL ROOM

Dear Sir:

In response to the Office Action of January 31, 1995,
applicant requests that the following changes be made to the
specification and claims.

In The Specification:

Page 1, line 29 after "will", delete the illegible word and
insert --generate--.

Page 1, line 36 after "22 of" delete the illegible word and
insert --p-doped--.

Page 2, line 36 after "Firstly," delete the illegible word and
insert --epitaxially--.

Page 4, line 29 after "not" delete the illegible word and insert
--bonded--.

In The Claims:

Amend claim 14 as indicated below.

14(Amended). A light emitting semiconductor device comprising:
an arrangement of semiconductor layers for generating light
in response to a conduction of current;
an optically transparent wafer-bond layer coupled to said

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